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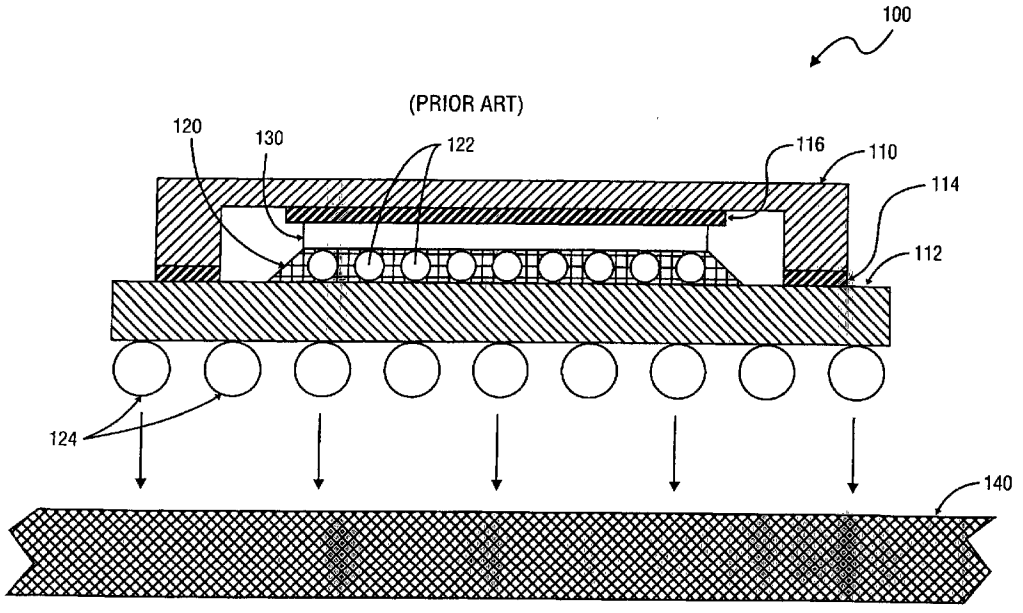
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(54) Title: IC PACKAGE PRESSURE RELEASE APPARATUS AND METHOD



(57) Abstract: An apparatus and method for releasing pressure existing within a package comprising a substrate to which a die is attached to provide electrical connections between the die and the exterior of the package, a lid, and sealant disposed between the substrate and the lid in a pattern with at least one break in the pattern.

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